



SSC8222GN2

N-Channel Enhancement Mode MOSFET

➤ Features

V_{DS}	V_{GS}	$R_{DS(ON)}$ Typ.	I_D
20V	$\pm 12V$	5.6m Ω @4V5	15A
		7.5m Ω @2V5	

➤ Description

This device is produced with high cell density DMOS trench technology, which is especially used to minimize on-state resistance. This device particularly suits low voltage applications such as portable equipment, power management and other battery powered circuits, and low in-line power dissipation are needed in a very small outline surface mount package.

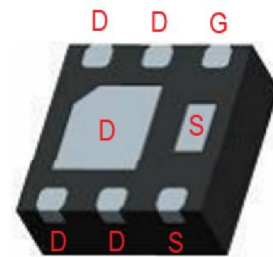
➤ Applications

- Load Switch
- Portable Devices
- DCDC Conversion
- Charging

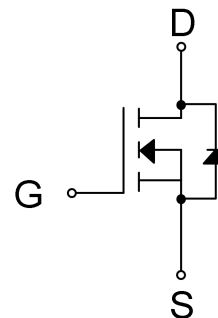
➤ Ordering Information

Device	Package	Shipping
SSC8222GN2	DFN2020-6L	3000/Reel

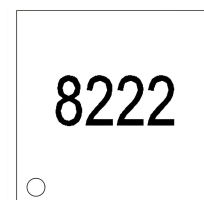
➤ Pin Configuration



DFN2020-6L (Bottom View)



Pin Configuration



Marking



➤ **Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

Parameter	Symbol	Ratings	Unit
Drain-to-Source Voltage	V_{DS}	20	V
Gate-to-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current ^d	I_D	15	A
Pulsed Drain Current ^b	I_{DM}	50	A
Power Dissipation ^c	P_D	2.8	W
Operation junction temperature	T_J	-25 to 85	$^{\circ}\text{C}$
Storage temperature range	T_{STG}	-55~150	$^{\circ}\text{C}$

➤ **Thermal Resistance Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

Parameter	Symbol	Maximum	Unit
Junction-to-Ambient Thermal Resistance ^a	$R_{\theta JA}$	61	$^{\circ}\text{C/W}$
Junction-to-Case Thermal Resistance	$R_{\theta JC}$	43	$^{\circ}\text{C/W}$

Note:

- The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The value in any given application depends on the user is specific board design. The power dissipation is based on the $t \leq 10\text{s}$ thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation P_D is based on $T_{J(MAX)}=150^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- The maximum current rating is package limited.

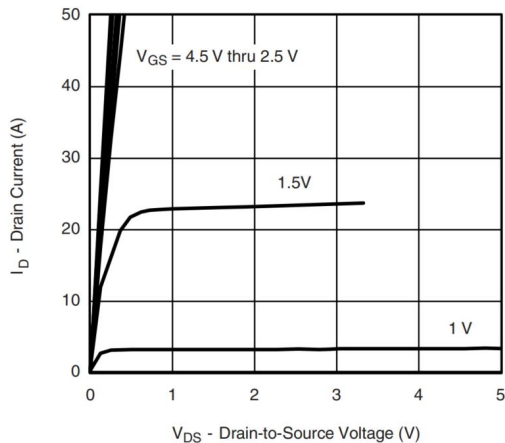


➤ **Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

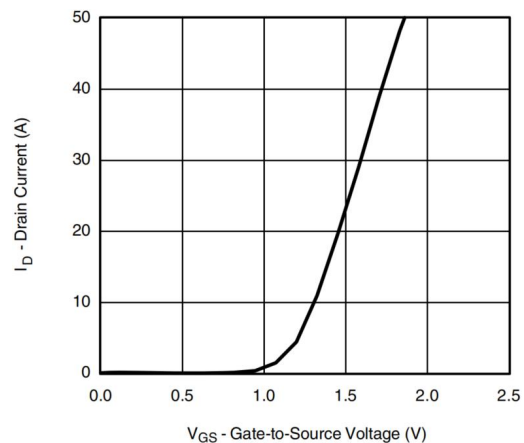
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	20			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.4	0.7	1	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 4.5V, I_D = 10A$		5.6	8	m Ω
		$V_{GS} = 2.5V, I_D = 5A$		7.5	10	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 16V, V_{GS} = 0V$			1	μA
Gate-Source Leak Current	I_{GSS}	$V_{GS} = \pm 12V, V_{DS} = 0V$			± 100	nA
Forward Transconductance	G_{FS}	$V_{DS}=5V, I_D=4.5A$		8		s
Forward Voltage	V_{SD}	$V_{GS} = 0V, I_S = 0.5A$		0.8	1.3	V
Input Capacitance	C_{ISS}	$V_{GS} = 0V, V_{DS} = 8V,$ $f = 1MHz$		1900		pF
Output Capacitance	C_{OSS}			430		
Reverse Transfer Capacitance	C_{RSS}			140		
Turn-on Delay Time	$T_{D(ON)}$	$V_{GEN} = 4.5V, V_{DS} = 10V,$ $R_L = 10\Omega, R_G = 6\Omega,$ $I_D = 1A$		20		ns
Turn-off Delay Time	$T_{D(OFF)}$			70		



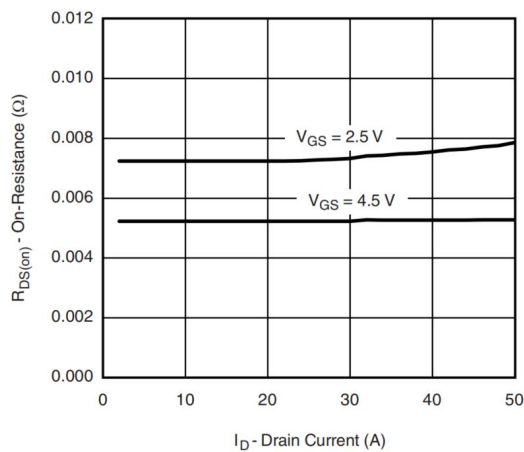
➤ Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)



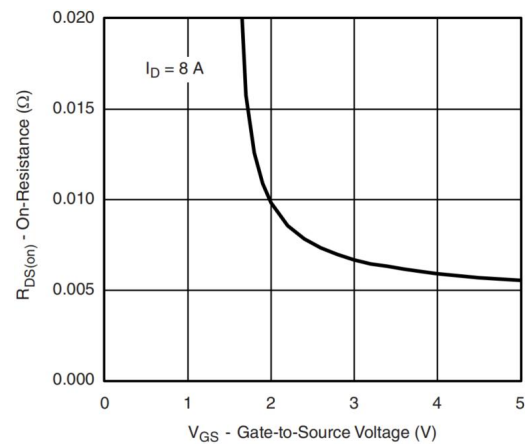
Output Characteristics



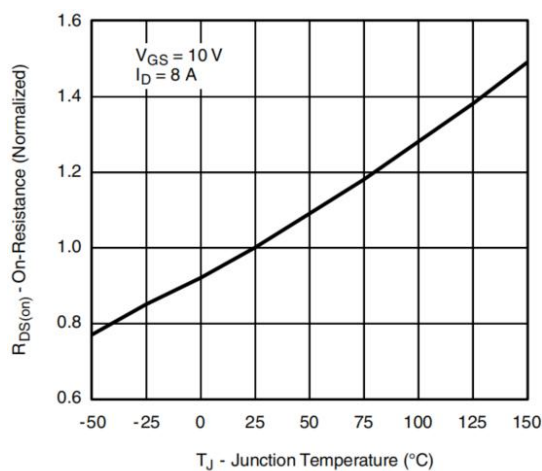
Transfer Characteristics



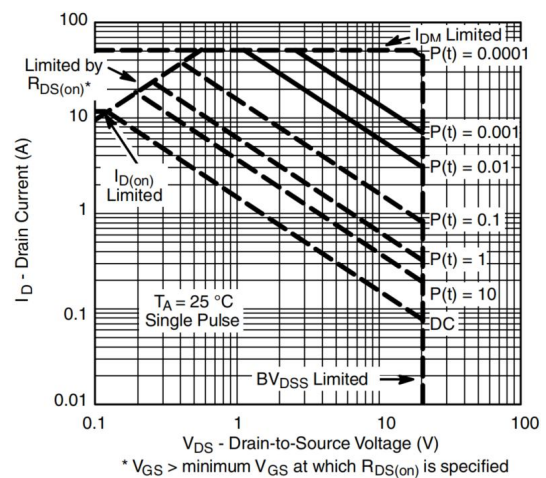
On-Resistance vs. Drain Current



On-Resistance vs. Gate-to-Source Voltage

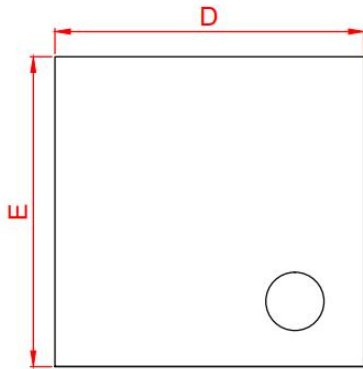


On-Resistance vs. Junction Temperature

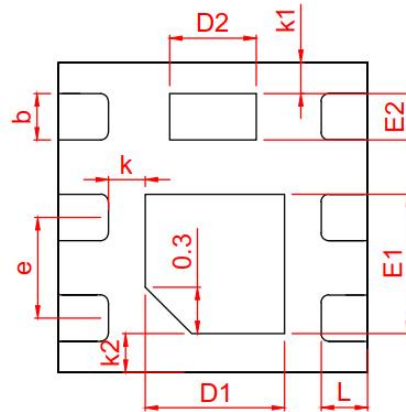


Safe Operating Area

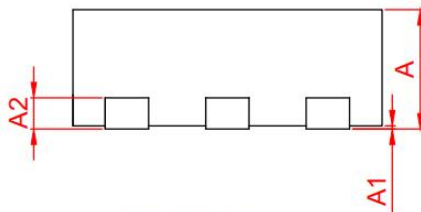
➤ Package Information



TOP VIEW



BOTTOM VIEW



SIDE VIEW

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.50	0.55	0.60
* A1	0.00	0.02	0.05
* b	0.25	0.30	0.35
* A2	0.152 BSC		
* D	1.95	2.00	2.05
* E	1.95	2.00	2.05
* E1	0.80	0.90	1.00
* E2	0.25	0.30	0.35
* D1	0.80	0.90	1.00
* D2	0.46	0.56	0.66
* e	0.65 REF		
* L	0.25	0.30	0.35
* K	0.20	0.25	0.30
* K1	0.15	0.20	0.25
* K2	0.20	0.25	0.30

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